2057403-1 V ACTIVE

IMPACT

TE Internal #: 2057403-1

60 Position, Mating Alignment, Guide Slot Mating Alignment Type, 6 Row, 10 Column, PCB Mount Receptacle, IMPACT, High Speed

Backplane Connectors

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Number of Positions: 60

Row-to-Row Spacing: 1.35 mm [.053 in]

Mating Alignment: With

Mating Alignment Type: Guide Slot

Number of Rows: 6

Features

Product Type Features

Signal Arrangement	Differential
Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Receptacle
Shroud Style	Unshrouded
Configuration Features	
Number of Ground Positions	20
Number of Pairs	20
Stackable	No
Number of Signal Positions	40
Number of Positions	60
Number of Rows	6
Number of Columns	10
PCB Mount Orientation	Right Angle



Electrical Characteristics Impedance 100 Q Operating Voltage 30 VAC Signal Characteristics Number of Differential Pairs per Column 2 Data Rate 20 – 25 Gb Body Features Primary Product Color Black Contact Features PCB Contact Termination Area Plating Material Thickness 1.27 µm[50] Contact Type Socket Contact Underplating Material Thickness 1.27 µm[50] Contact Mating Area Plating Material Thickness 7.62 µm[30] Contact Mating Area Plating Material Thickness 7.62 µm[50] Contact Mating Area Plating Material Finish Matte Contact Shape & Form Dual Beam Contact Underplating Material Nickel PCB Contact Termination Area Plating Material PCB Contact Termination Area Plating Material Contact Underplating Material Contact Underplating Material Contact Underplating Material Contact Underplating Material Tin Contact Base Material Contact Current Rating (Max) Termination Features Termination Post & Tail Length Termination Method to PCB Through H Mechanical Attachment	/s
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PCB Mount Alignment Type Locating P	
Guide Hardware With	ole - Press-Fit
Mating Retention Without	ole - Press-Fit
PCB Mount Retention With	ole - Press-Fit
PCB Mount Retention Type Action/Con	ole - Press-Fit
Mating Alignment With	ole - Press-Fit



Mating Alignment Type	Guide Slot
Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	0
End Wall Location	None
Housing Material	LCP - GF (Liquid Crystal Polymer)
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	26.6 mm[1.047 in]
Connector Height	10.9 mm[.429 in]
Connector Width	20.1 mm[.791 in]
PCB Thickness (Recommended)	1.6 mm
PCB Hole Diameter	.39 mm[.015 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Compatible With Approved Standards Products	CSA Certified, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tube, Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241)



Does	not	contain	REACH	SVHC
	1100	COITLAIL	$1 \times 1 \times$	\cup

Free	homogenous material. Also BFR/CFR/PVC	Halogen Content Low Halogen - Br, Cl, F, I < 900 ppm per
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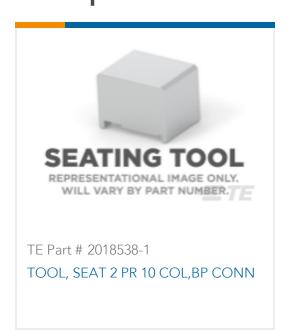
Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

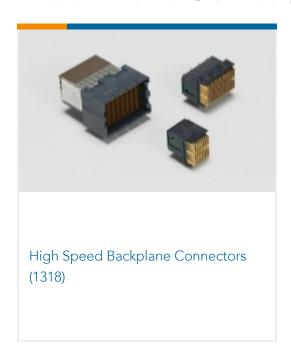
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | IMPACT

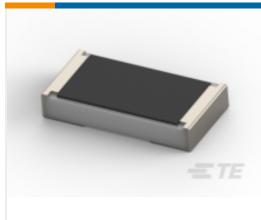


Customers Also Bought



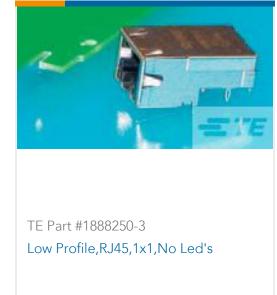


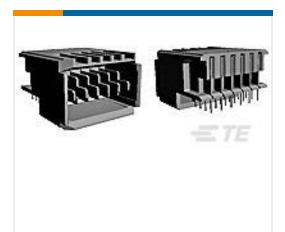
TE Part #3-338309-2 9POS.HD20 PLUG ASSY



TE Part #4-2176231-9
SMD Power Resistor: 3 Watt, 1% Tol







TE Part #120956-1

UPM EXPANDED PIN ASSEMBLY



Documents

Product Drawings

IMP100S,R,RA2P10C,LG,39

English

CAD Files

Customer View Model

ENG_CVM_CVM_2057403-1_A.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2057403-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2057403-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

7-1773458-1_IMPACT_BACKPLANE_CONNECTOR_SYSTEM_CATALOG

English

Product Specifications

Application Specification

English

Agency Approvals

Agency Approval Document

60 Position, Mating Alignment, Guide Slot Mating Alignment Type, 6 Row, 10 Column, PCB Mount Receptacle, IMPACT, High Speed Backplane Connectors



English